

SN74LVC16244A 16-Bit Buffer/Driver With 3-State Outputs

1 Features

- Member of the Texas Instruments Widebus™ Family
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4.1 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} Supports Live Insertion, Partial-Power-Down Mode, and Back-Drive Protection
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

2 Applications

- Servers
- PCs and Notebooks
- Network Switches
- Wireless and Telecom Infrastructures
- TV Set-top Boxes
- Electronic Points of Sale

3 Description

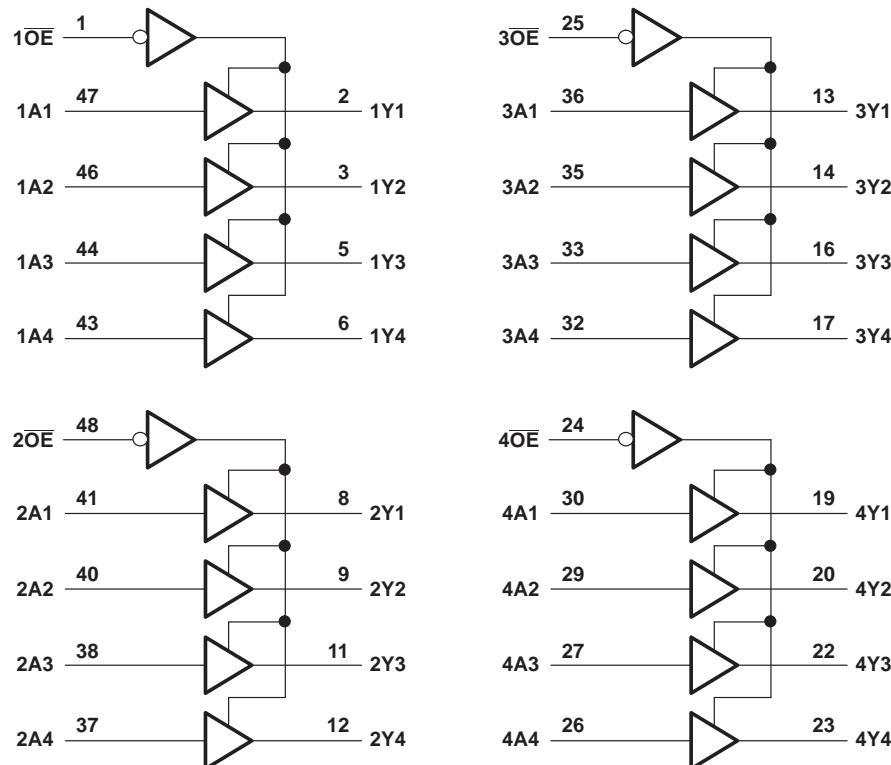
This 16-bit buffer/driver is designed for 1.65-V to 3.6-V V_{CC} operation. The SN74LVC16244A device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
	TSSOP (48)	12.50 mm × 6.10 mm
SN74LVC16244A	TVSOP (48)	9.70 mm × 4.40 mm
	SSOP (48)	15.88 mm × 7.49 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Simplified Schematic



Pin numbers shown are for the DGG, DGV, and DL packages.



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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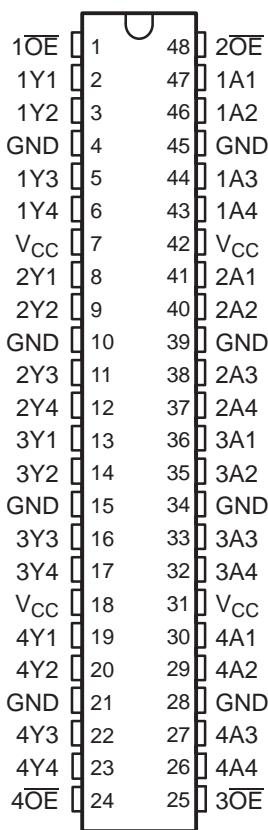
5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (April 2009) to Revision C	Page
• Updated document to new TI data sheet format.	1
• Deleted Ordering Information table.	1
• Updated I_{off} Feature bullet.	1
• Added Applications.	1
• Added Device Information table.	1
• Added Handling Ratings table.	6
• Changed MAX operating free-air temperature from 85°C to 125°C .	7
• Added Thermal Information table.	7
• Added -40°C TO 125°C temperature range to Electrical Characteristics table.	8
• Added Switching Characteristics table for -40°C TO 125°C temperature range.	9
• Added Typical Characteristics.	9

6 Pin Configuration and Functions

**DGG, DGV, OR DL PACKAGE
(TOP VIEW)**



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	1OE	I	Output enable 1
2	1Y1	O	1Y1 Output
3	1Y2	O	1Y2 Output
4	GND	—	Ground pin
5	1Y3	O	1Y3 Output
6	1Y4	O	1Y4 Output
7	VCC	—	Power pin
8	2Y1	O	2Y1 Output
9	2Y2	O	2Y2 Output
10	GND	—	Ground pin
11	2Y3	O	2Y3 Output
12	2Y4	O	2Y4 Output
13	3Y1	O	3Y1 Output
14	3Y2	O	3Y2 Output
15	GND	—	Ground pin
16	3Y3	O	3Y3 Output
17	3Y4	O	3Y4 Output
18	VCC	—	Power pin

Pin Functions (continued)

PIN		I/O	DESCRIPTION
NO.	NAME		
19	4Y1	O	4Y1 Output
20	4Y2	O	4Y2 Output
21	GND	—	Ground pin
22	4Y3	O	4Y3 Output
23	4Y4	O	4Y4 Output
24	$4\overline{OE}$	I	Output enable 4
25	$3\overline{OE}$	I	Output enable 3
26	4A4	I	4A4 Input
27	4A3	I	4A3 Input
28	GND	—	Ground pin
29	4A2	I	4A2 Input
30	4A1	I	4A1 Input
31	VCC	—	Power pin
32	3A4	I	3A4 Input
33	3A3	I	3A3 Input
34	GND	—	Ground pin
35	3A2	I	3A2 Input
36	3A1	I	3A1 Input
37	2A4	I	2A4 Input
38	2A3	I	2A3 Input
39	GND	—	Ground pin
40	2A2	I	2A2 Input
41	2A1	I	2A1 Input
42	VCC	—	Power pin
43	1A4	I	1A4 Input
44	1A3	I	1A3 Input
45	GND	—	Ground pin
46	1A2	I	1A2 Input
47	1A1	I	1A1 Input
48	$2\overline{OE}$	I	Output enable 2

GQL OR ZQL PACKAGE (TOP VIEW)

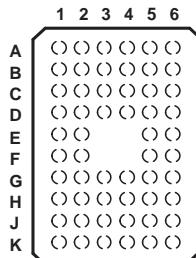


Table 1. Pin Assignments⁽¹⁾ (56-Ball GQL or ZQL Package)

	1	2	3	4	5	6
A	1 \overline{OE}	NC	NC	NC	NC	2 \overline{OE}
B	1Y2	1Y1	GND	GND	1A1	1A2
C	1Y4	1Y3	V_{CC}	V_{CC}	1A3	1A4
D	2Y2	2Y1	GND	GND	2A1	2A2
E	2Y4	2Y3				2A3
F	3Y1	3Y2				3A2
G	3Y3	3Y4	GND	GND	3A4	3A3
H	4Y1	4Y2	V_{CC}	V_{CC}	4A2	4A1
J	4Y3	4Y4	GND	GND	4A4	4A3
K	4 \overline{OE}	NC	NC	NC	NC	3 \overline{OE}

(1) NC – No internal connection

**GRD OR ZRD PACKAGE
(TOP VIEW)**

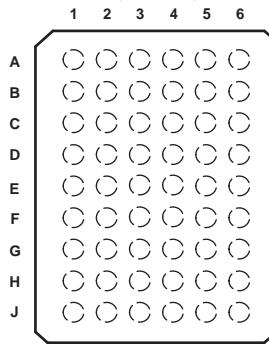


Table 2. Pin Assignments⁽¹⁾ (54-Ball GRD or ZRD Package)

	1	2	3	4	5	6
A	1Y1	NC	$1\overline{OE}$	$2\overline{OE}$	NC	1A1
B	1Y3	1Y2	NC	NC	1A2	1A3
C	2Y1	1Y4	V_{CC}	V_{CC}	1A4	2A1
D	2Y3	2Y2	GND	GND	2A2	2A3
E	3Y1	2Y4	GND	GND	2A4	3A1
F	3Y3	3Y2	GND	GND	3A2	3A3
G	4Y1	3Y4	V_{CC}	V_{CC}	3A4	4A1
H	4Y3	4Y2	NC	NC	4A2	4A3
J	4Y4	NC	$4\overline{OE}$	$3\overline{OE}$	NC	4A4

(1) NC – No internal connection

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	–0.5	6.5	V
V_I	Input voltage range ⁽²⁾	–0.5	6.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	–0.5	6.5	V
V_O	Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾	–0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	–50	mA
I_{OK}	Output clamp current	$V_O < 0$	–50	mA
I_O	Continuous output current		±50	mA
	Continuous current through each V_{CC} or GND		±100	mA

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the *Recommended Operating Conditions* table.

7.2 Handling Ratings

		MIN	MAX	UNIT
T_{stg}	Storage temperature range	–65	150	°C
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	0	2000
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	0	1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 2.7 V to 3.6 V	0.8		
V _I	Input voltage		0	5.5	V
V _O	Output voltage	High or low state	0	V _{CC}	V
		3-state	0	5.5	
I _{OH}	High-level output current	V _{CC} = 1.65 V		-4	mA
		V _{CC} = 2.3 V		-8	
		V _{CC} = 2.7 V		-12	
		V _{CC} = 3 V		-24	
I _{OL}	Low-level output current	V _{CC} = 1.65 V		4	mA
		V _{CC} = 2.3 V		8	
		V _{CC} = 2.7 V		12	
		V _{CC} = 3 V		24	
Δt/Δv	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾	DGG	DGV	DL	UNIT
	48 PINS	48 PINS	48 PINS	
R _{θJA}	64.3	78.4	68.4	°C/W
R _{θJC(top)}	17.6	30.7	34.7	
R _{θJB}	31.5	41.8	41.0	
Ψ _{JT}	1.1	3.8	12.3	
Ψ _{JB}	31.2	41.3	40.4	
R _{θJC(bot)}	n/a	n/a	n/a	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

7.5 Electrical Characteristics—DC Limit Changes

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	-40°C TO 85°C			-40°C TO 125°C			UNIT	
			MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX		
V _{OH}	I _{OH} = -100 µA	1.65 V to 3.6 V	V _{CC} – 0.2			V _{CC} – 0.2			V	
	I _{OH} = -4 mA	1.65 V	1.2			1.2				
	I _{OH} = -8 mA	2.3 V	1.7			1.7				
	I _{OH} = -12 mA	2.7 V	2.2			2.2				
		3 V	2.4			2.4				
V _{OL}	I _{OL} = 100 µA	1.65 V to 3.6 V	0.2			0.2			V	
	I _{OL} = 4 mA	1.65 V	0.45			0.45				
	I _{OL} = 8 mA	2.3 V	0.7			0.7				
	I _{OL} = 12 mA	2.7 V	0.4			0.4				
	I _{OL} = 24 mA	3 V	0.55			0.55				
I _I	V _I = 0 to 5.5 V	3.6 V	±5			±5			µA	
I _{off}	V _I or V _O = 5.5 V	0	±10			±20			µA	
I _{OZ}	V _O = 0 to 5.5 V	3.6 V	±10			±10			µA	
I _{CC}	V _I = V _{CC} or GND 3.6 V ≤ V _I ≤ 5.5 V ⁽²⁾	I _O = 0	3.6 V	20			20			
				20			20			
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V	500			500			
C _i	V _I = V _{CC} or GND		3.3 V	5.5						
C _o	V _O = V _{CC} or GND		3.3 V	6						

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This applies in the disabled state only.

7.6 Switching Characteristics, -40°C to 85°C

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-40°C TO 85°C								UNIT	
			$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$		$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CC} = 2.7 \text{ V}$		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$			
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t_{pd}	A	Y	1.5	6.6	1	3.9	1	4.7	1.1	4.1	ns	
t_{en}	\overline{OE}	Y	1.5	7.5	1	4.7	1	5.8	1.0	4.6	ns	
t_{dis}	\overline{OE}	Y	1.5	10.3	1	5.3	1	6.2	1.8	5.8	ns	
$t_{sk(o)}$										1	ns	

7.7 Switching Characteristics, -40°C to 125°C

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

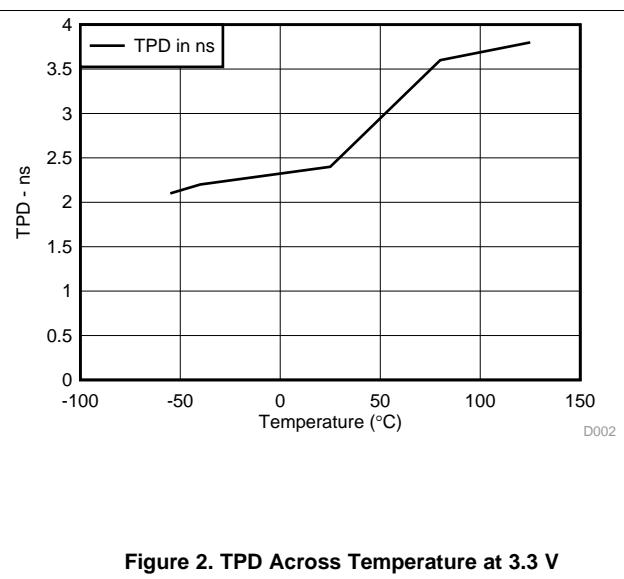
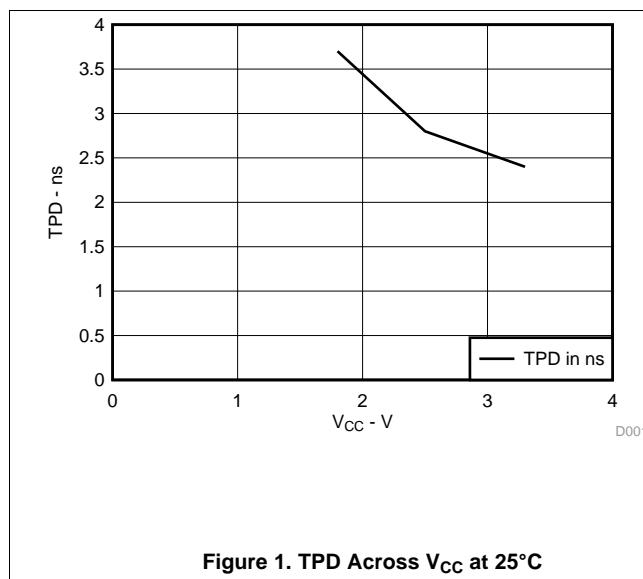
PARAMETER	FROM (INPUT)	TO (OUTPUT)	-40°C TO 125°C								UNIT	
			$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$		$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CC} = 2.7 \text{ V}$		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$			
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t_{pd}	A	Y	1.5	7.1	1	4.4	1	5.2	1.1	4.6	ns	
t_{en}	\overline{OE}	Y	1.5	8.0	1	6.0	1	6.3	1.0	5.1	ns	
t_{dis}	\overline{OE}	Y	1.5	10.8	1	5.7	1	6.7	1.8	6.3	ns	
$t_{sk(o)}$										1.5	ns	

7.8 Operating Characteristics

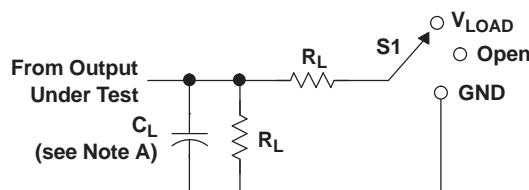
$T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8 \text{ V}$	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	UNIT
		TYP	TYP	TYP	
		MIN	MAX	MIN	
C_{pd}	Power dissipation capacitance per buffer/driver	33	35	39	pF
		2	3	4	

7.9 Typical Characteristics



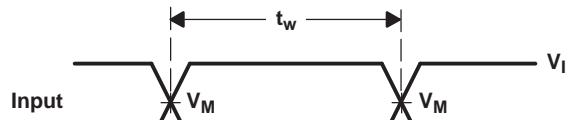
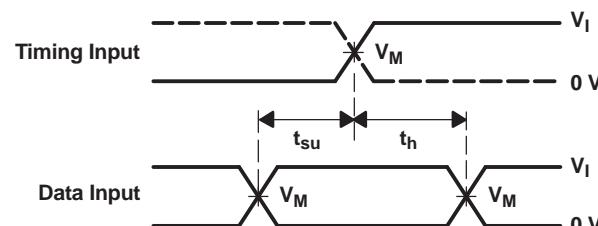
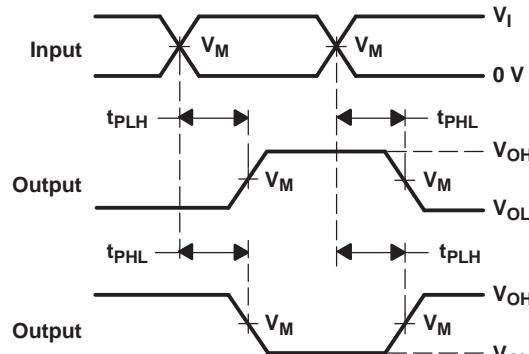
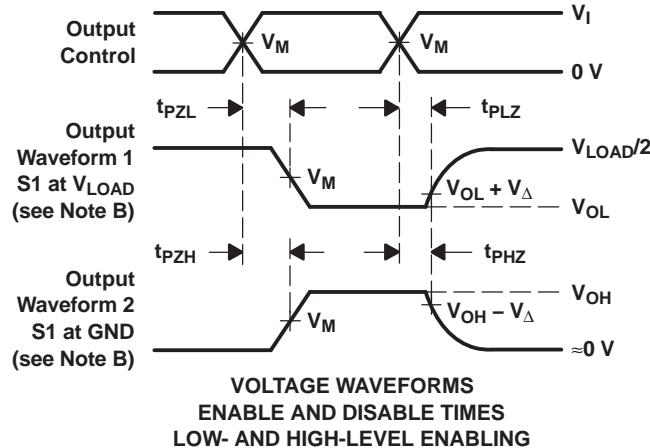
8 Parameter Measurement Information



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
$1.8 \text{ V} \pm 0.15 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V

VOLTAGE WAVEFORMS
PULSE DURATIONVOLTAGE WAVEFORMS
SETUP AND HOLD TIMESVOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTSVOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$.
- The outputs are measured one at a time, with one transition per measurement.
- t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- t_{PZL} and t_{PZH} are the same as t_{en} .
- t_{PLH} and t_{PHL} are the same as t_{pd} .
- All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

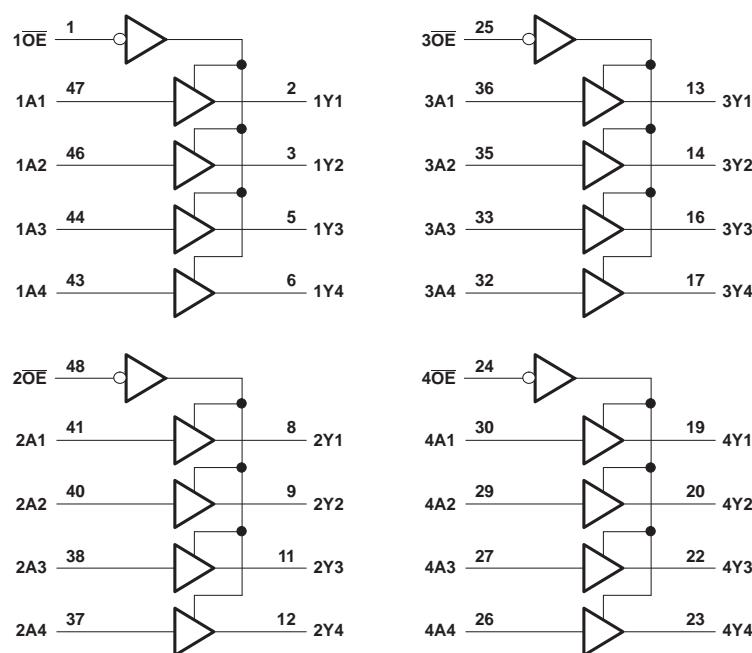
9 Detailed Description

9.1 Overview

This 16-bit buffer/driver is designed for 1.65-V to 3.6-V V_{CC} operation. The SN74LVC16244A device is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. It provides true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

9.2 Functional Block Diagram



Pin numbers shown are for the DGG, DGV, and DL packages.

9.3 Feature Description

- Wide operating voltage range
 - Operates from 1.65 V to 3.6 V
- Allows down voltage translation
 - Inputs accept voltages to 5.5 V
- I_{off} feature
 - Allows voltages on the inputs and outputs when V_{CC} is 0 V

9.4 Device Functional Modes

**Table 3. Function Table
(Each 4-bit Buffer)**

INPUTS		OUTPUT Y
\overline{OE}	A	
L	H	H
L	L	L
H	X	Z

10 Application and Implementation

10.1 Application Information

The SN74LVC16244A device is a 16-bit buffer/driver. This device can be used as four 4-bit, two 8-bit, or one 16-bit buffer. It allows data transmission from the A bus to the Y bus with 4 separate enable pins that control 4 bits each. The output-enable (OE) input can be used to disable sections of the device so that the buses are effectively isolated. The device has 5.5 V tolerant inputs at any valid V_{CC} which allows it to be used in multi-power systems and can be used for down translation.

10.2 Typical Application

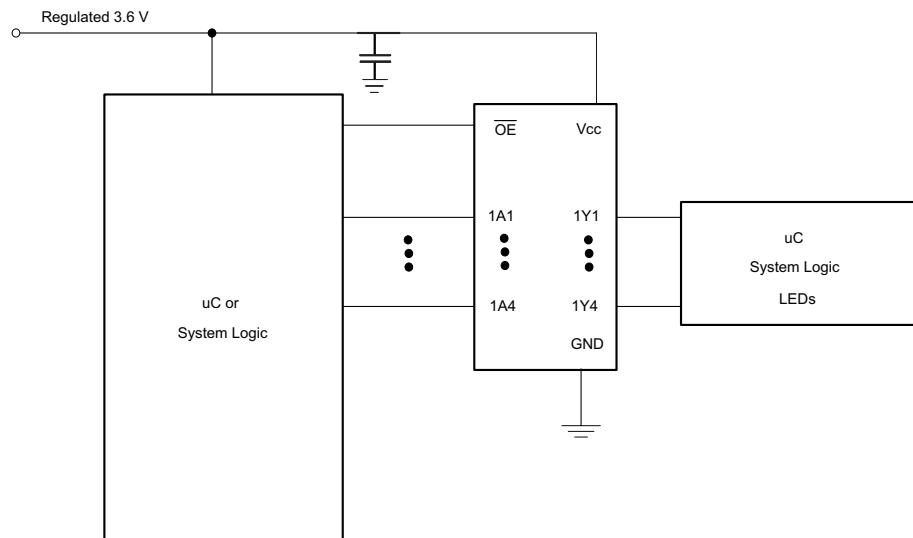


Figure 4. Typical Application Diagram

10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads; therefore, routing and load conditions should be considered to prevent ringing.

10.2.2 Detailed Design Procedure

1. Recommended Input Conditions

- Rise time and fall time specs: See ($\Delta t/\Delta V$) in the [Recommended Operating Conditions](#) table.
- Specified high and low levels: See (V_{IH} and V_{IL}) in the [Recommended Operating Conditions](#) table.
- Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .

2. Recommend Output Conditions

- Load currents should not exceed 25 mA per output and 50 mA total for the part.
- Outputs should not be pulled above V_{CC} .

Typical Application (continued)

10.2.3 Application Curves

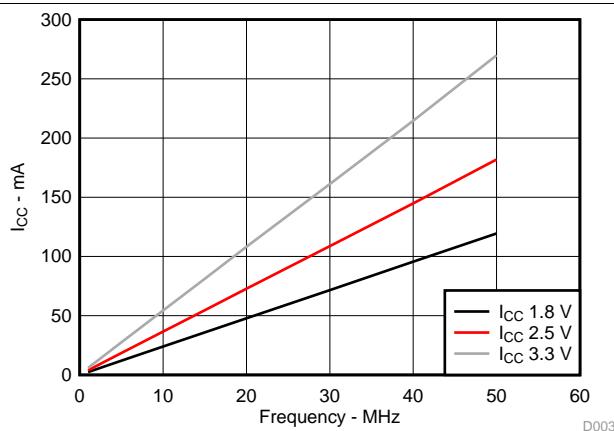


Figure 5. I_{CC} vs Frequency

D003

11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Recommended Operating Conditions* table.

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 μ F is recommended; if there are multiple V_{CC} pins, then 0.01 μ F or 0.022 μ F is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 μ F and a 1 μ F are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

12 Layout

12.1 Layout Guidelines

When using multiple-bit logic devices, inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Figure 6 specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the output section of the part when asserted. This will not disable the input section of the I/Os, so they cannot float when disabled.

12.2 Layout Example

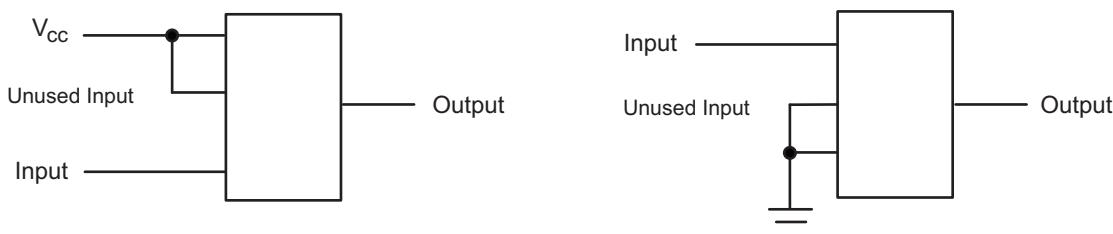


Figure 6. Layout Diagram

13 Device and Documentation Support

13.1 Trademarks

Widebus is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74LVC16244ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16244A	Samples
SN74LVC16244ADGG	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16244A	Samples
SN74LVC16244ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16244A	Samples
SN74LVC16244ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LD244A	Samples
SN74LVC16244ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16244A	Samples
SN74LVC16244ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16244A	Samples
SN74LVC16244ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16244A	Samples
SN74LVC16244ADLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC16244A	Samples
SN74LVC16244AGQLR	OBsolete	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85	LD244A	
SN74LVC16244AGRDR	OBsolete	BGA MICROSTAR JUNIOR	GRD	54		TBD	Call TI	Call TI	-40 to 85		
SN74LVC16244AZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LD244A	Samples
SN74LVC16244AZRDR	ACTIVE	BGA MICROSTAR JUNIOR	ZRD	54	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LD244A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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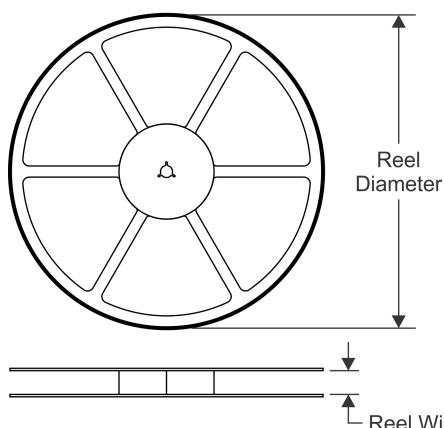
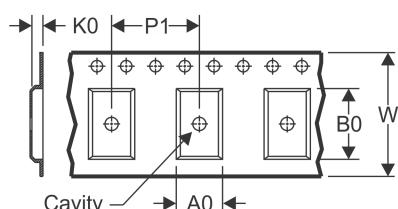
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVC16244A :

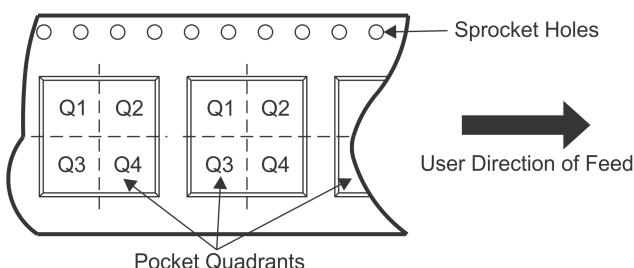
- Automotive: [SN74LVC16244A-Q1](#)
- Enhanced Product: [SN74LVC16244A-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

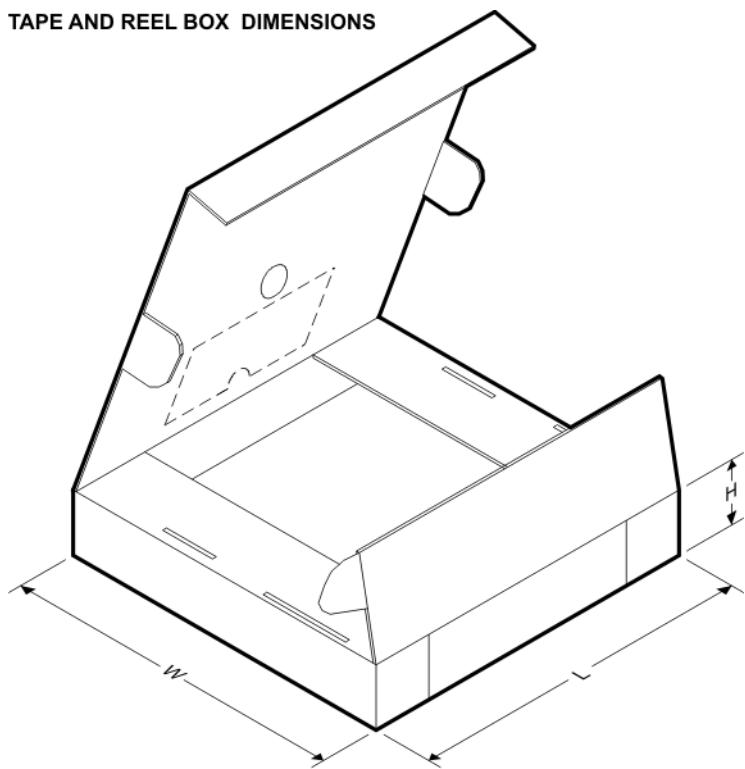
TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC16244ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74LVC16244ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74LVC16244ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74LVC16244AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74LVC16244AZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	330.0	16.4	5.8	8.3	1.55	8.0	16.0	Q1

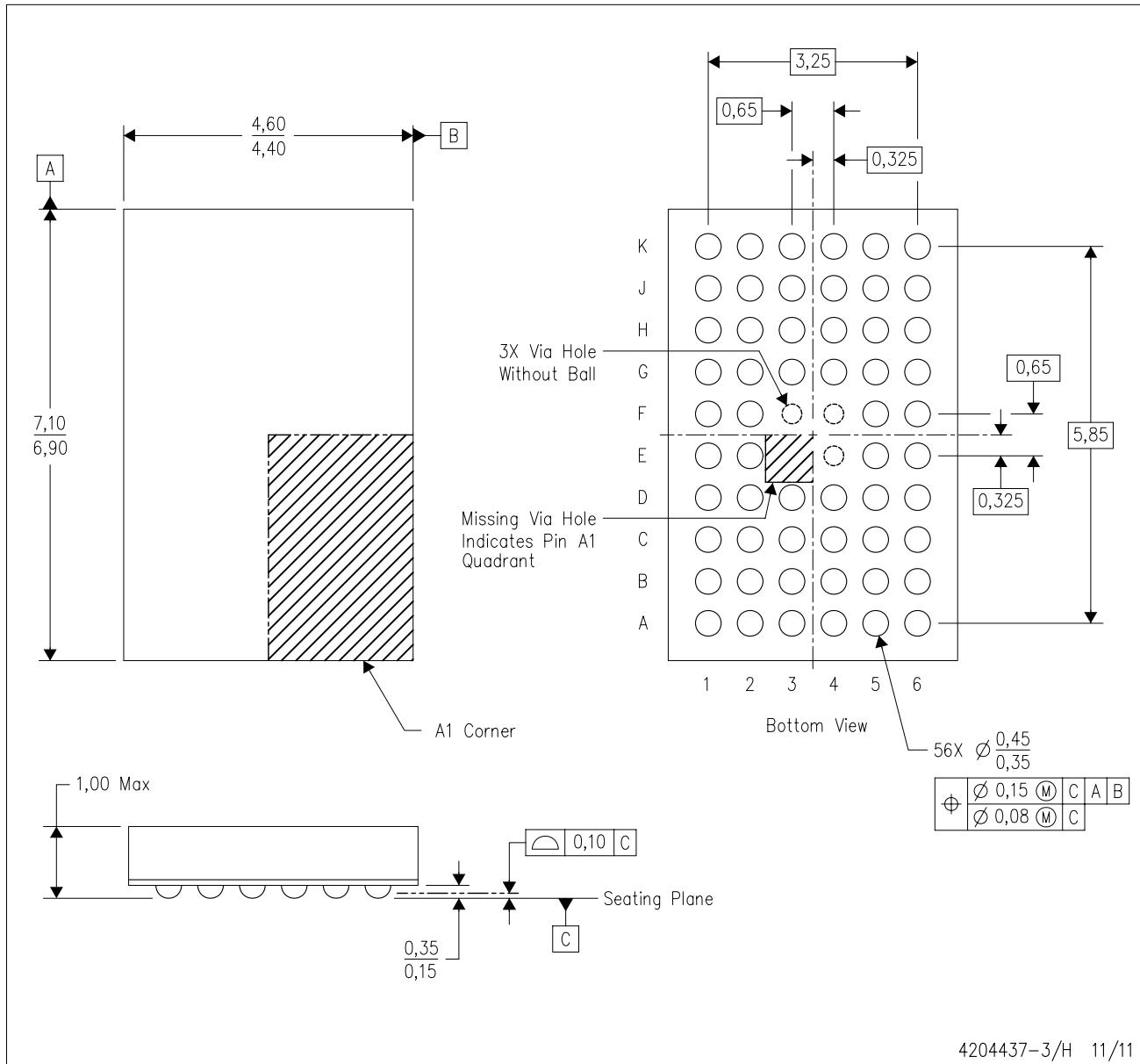
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC16244ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74LVC16244ADGVR	TVSOP	DGV	48	2000	367.0	367.0	38.0
SN74LVC16244ADLR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74LVC16244AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	336.6	336.6	28.6
SN74LVC16244AZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	336.6	336.6	28.6

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY

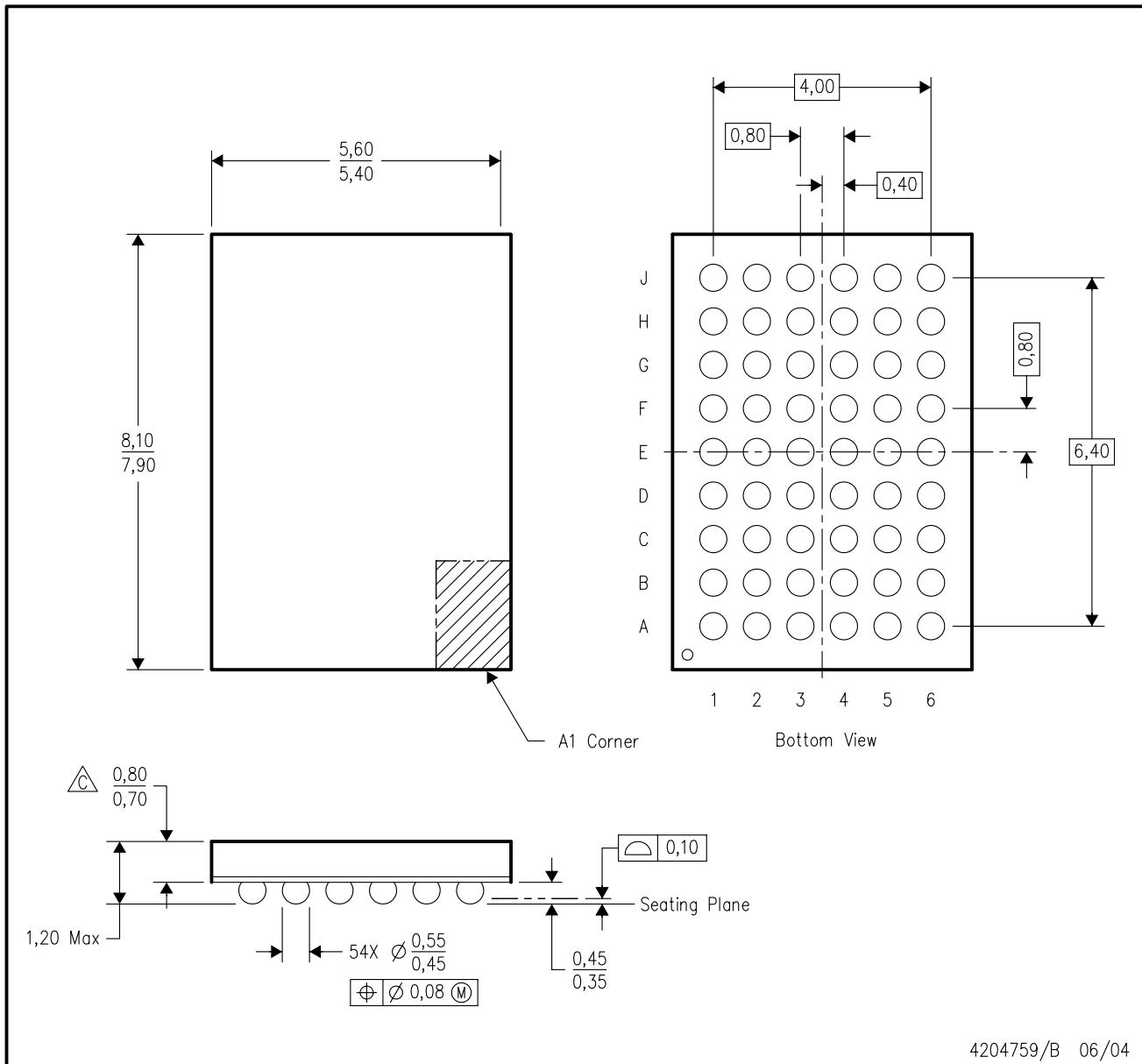


NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Falls within JEDEC MO-285 variation BA-2.
- This package is Pb-free. Refer to the 56 QGL package (drawing 4200583) for tin-lead (SnPb).

GRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



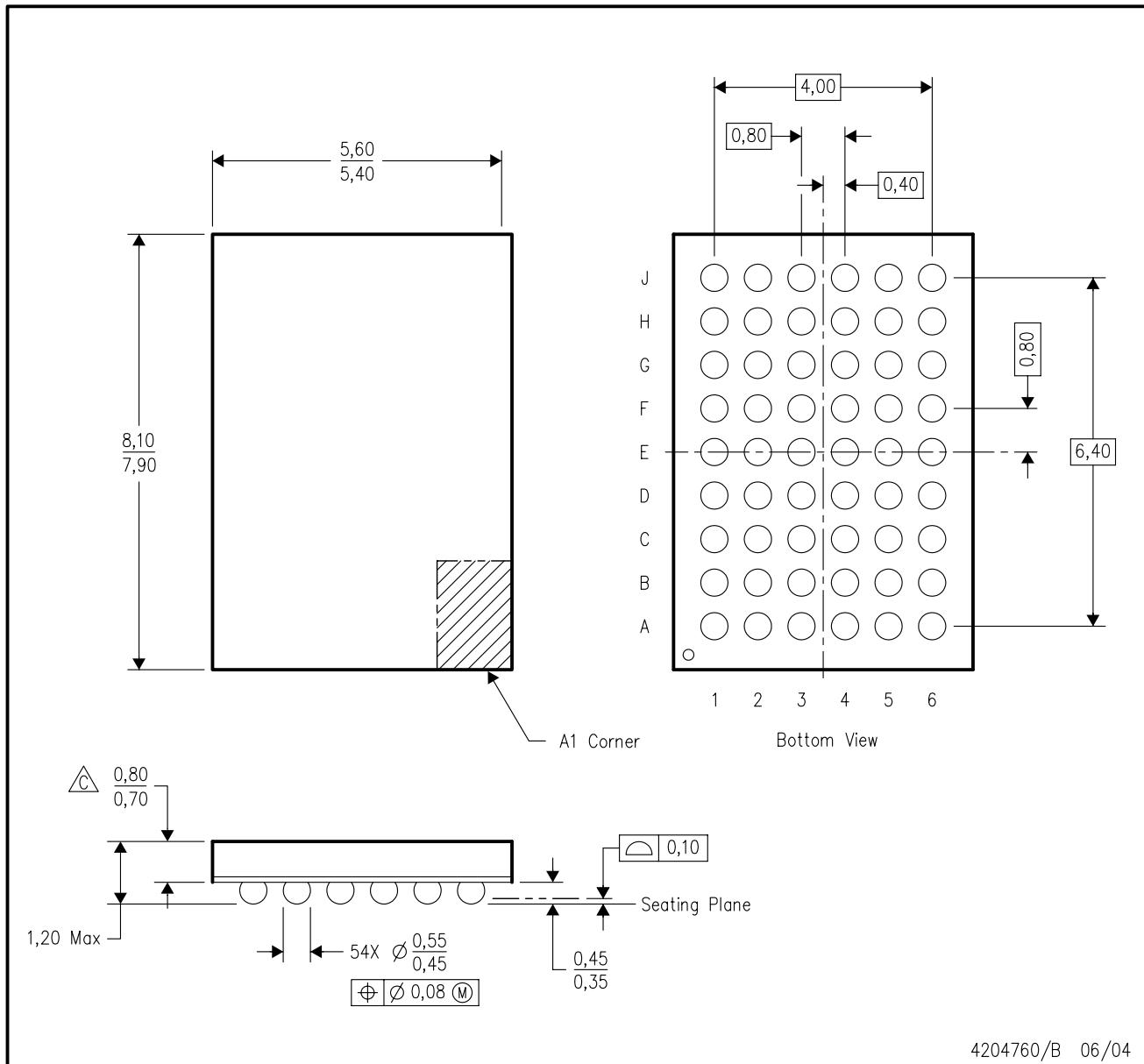
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.

Falls within JEDEC MO-205 variation DD.

D. This package is tin-lead (SnPb). Refer to the 54 ZRD package (drawing 4204760) for lead-free.

ZRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



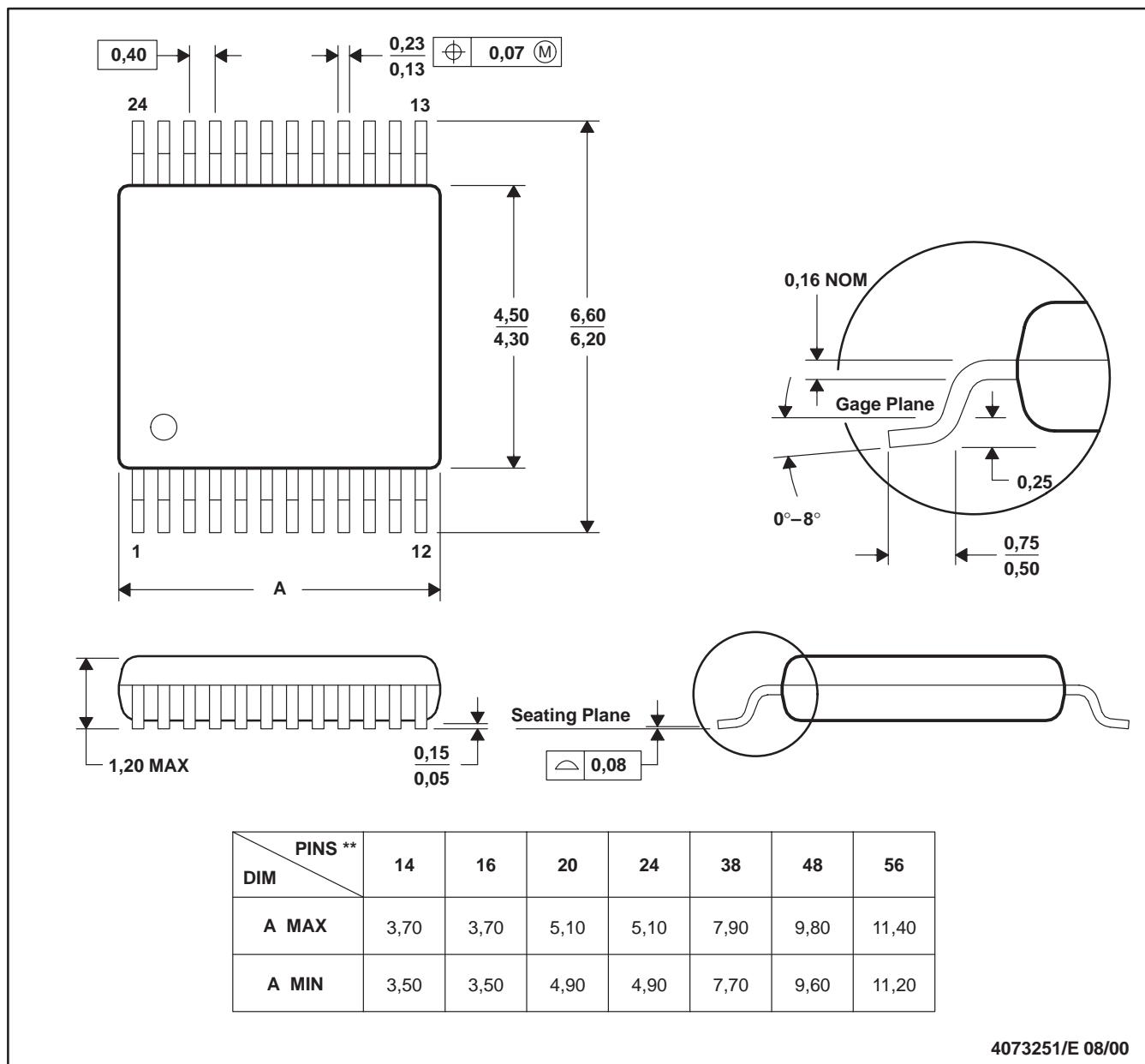
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-205 variation DD.
- D. This package is lead-free. Refer to the 54 GRD package (drawing 4204759) for tin-lead (SnPb).

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

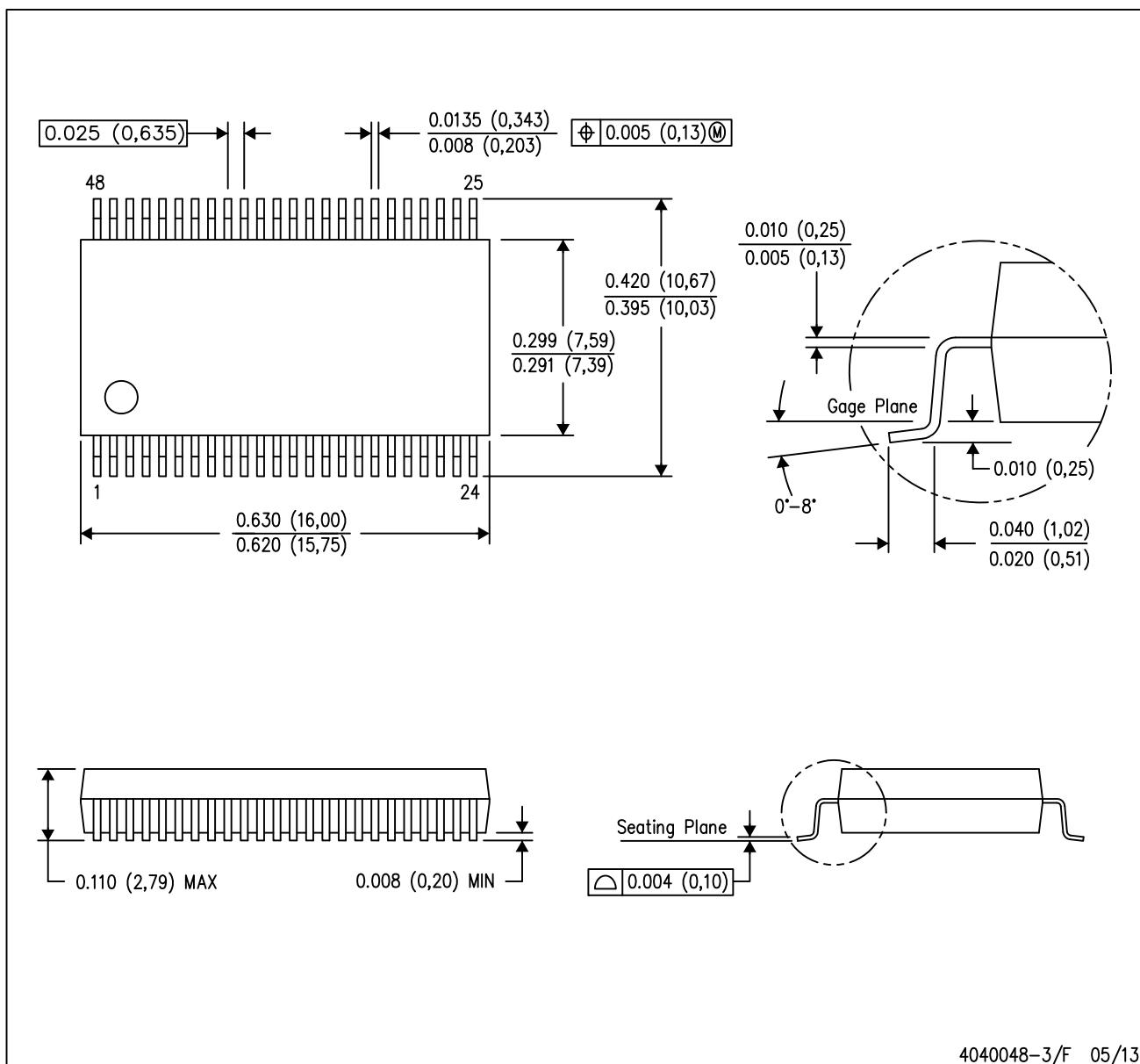
24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



4040048-3/F 05/13

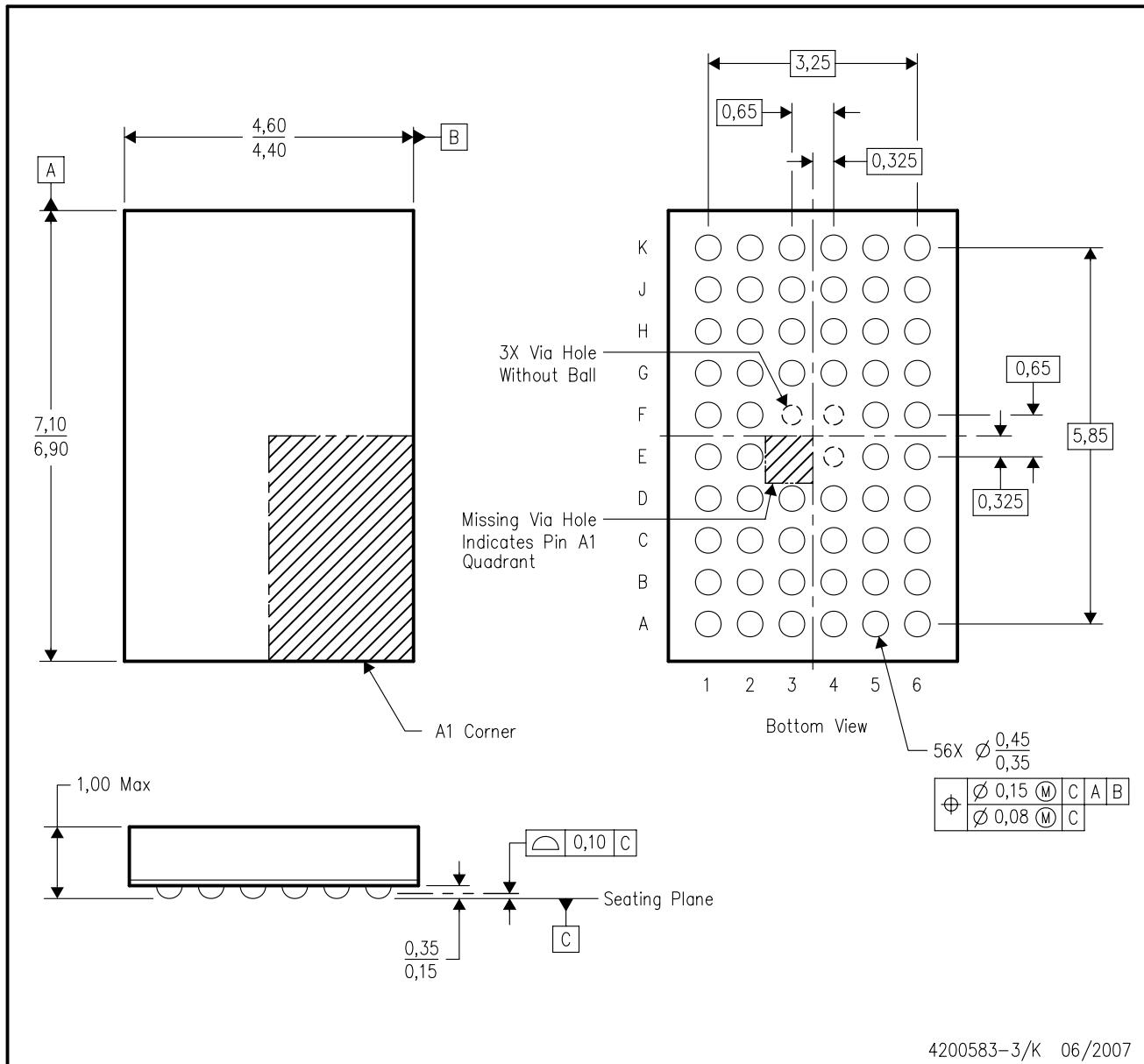
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



4200583-3/K 06/2007

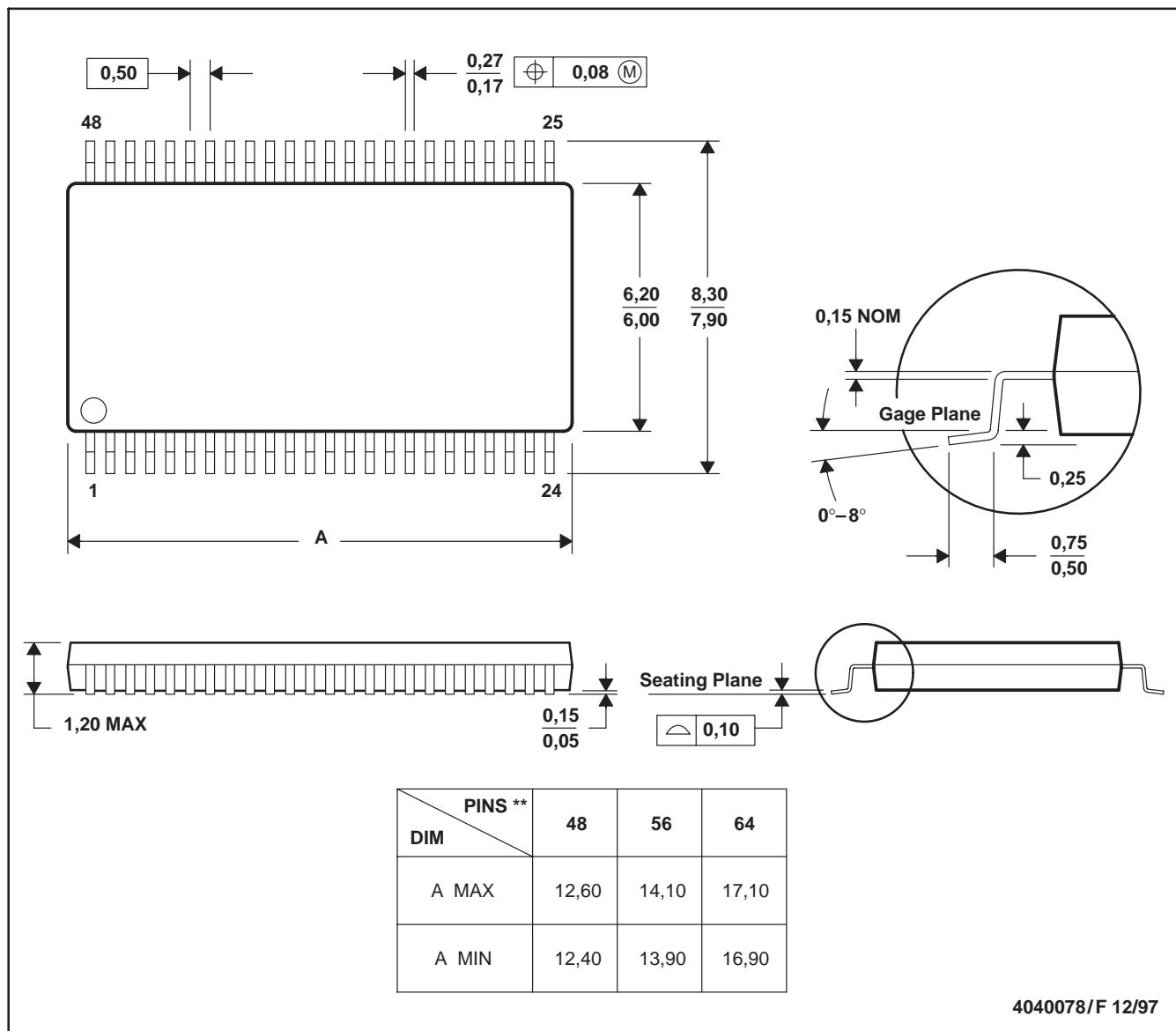
NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Falls within JEDEC MO-285 variation BA-2.
- This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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